



Product / Package Information	
Package	SC70
Body Size	
Lead Count	6
Terminal Finish	100 Sn
MS Number	MS012335C

Environmental Compliance Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.58 E-03	87.70	877000	37.72	377244
Thermosets	Epoxy Resin	Proprietary	1.47 E-04	5.00	50000	2.15	21508
Thermosets	Phenol Resin	Proprietary	1.47 E-04	5.00	50000	2.15	21508
Thermosets	Epoxy Cresol Novolac	29690-82-2	5.87 E-05	2.00	20000	0.86	8603
Other inorganic materials	Carbon Black	1333-86-4	8.81 E-06	0.30	3000	0.13	1290
Subtotal			2.94 E-03	100.0	1000000	43.02	430152

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.20 E-03	97.5	975000	46.82	468248
Copper & its alloys	Iron	7439-89-6	7.70 E-05	2.35	23500	1.13	11286
Copper & its alloys	Zinc	7440-66-6	3.93 E-06	0.12	1200	0.06	576
Copper & its alloys	Phosphorus	7723-14-0	9.84 E-07	0.03	300	0.01	144
Subtotal			3.28 E-03	100	1000000	48.03	480255

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.31 E-05	100	1000000	0.49	4851

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.42 E-04	100	1000000	3.55	35473

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.88 E-05	99.99	1000000	0.57	5685

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	2.72 E-04	100	1000000	3.98	39794

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.07 E-05	80.00	800000	0.30	3032
Other organic materials	bisphenol-F-(epichlorhydrin); epoxy resin	9003-36-5	3.88 E-06	15.00	150000	0.06	568
Other organic materials	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	6.47 E-07	2.50	25000	0.01	95
Other organic materials	Dapsone	80-08-0	6.47 E-07	2.50	25000	0.01	95
Subtotal			2.59 E-05	100.00	1000000	0.38	3790

Package Totals	Weight (g)	Percentage (%)	PPM
	6.83 E-03	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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